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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	2500
Number of I/O	96
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm3128atc144-7

...and More Features

- PCI compatible
- Bus–friendly architecture including programmable slew–rate control
- Open–drain output option
- Programmable macrocell flipflops with individual clear, preset, clock, and clock enable controls
- Programmable power–saving mode for a power reduction of over 50% in each macrocell
- Configurable expander product–term distribution, allowing up to 32 product terms per macrocell
- Programmable security bit for protection of proprietary designs
- Enhanced architectural features, including:
  - 6 or 10 pin– or logic–driven output enable signals
  - Two global clock signals with optional inversion
  - Enhanced interconnect resources for improved routability
  - Programmable output slew–rate control
- Software design support and automatic place–and–route provided by Altera's development systems for Windows–based PCs and Sun SPARCstations, and HP 9000 Series 700/800 workstations
- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from third–party manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, Synplicity, and VeriBest
- Programming support with the Altera master programming unit (MPU), MasterBlaster™ communications cable, ByteBlasterMV™ parallel port download cable, BitBlaster™ serial download cable as well as programming hardware from third–party manufacturers and any in–circuit tester that supports Jam™ Standard Test and Programming Language (STAPL) Files (**.jam**), Jam STAPL Byte-Code Files (**.jbc**), or Serial Vector Format Files (**.svf**)

General Description

MAX 3000A devices are low–cost, high–performance devices based on the Altera MAX architecture. Fabricated with advanced CMOS technology, the EEPROM–based MAX 3000A devices operate with a 3.3-V supply voltage and provide 600 to 10,000 usable gates, ISP, pin-to-pin delays as fast as 4.5 ns, and counter speeds of up to 227.3 MHz. MAX 3000A devices in the –4, –5, –6, –7, and –10 speed grades are compatible with the timing requirements of the PCI Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2*. See Table 2.

MAX 3000A devices contain 32 to 512 macrocells, combined into groups of 16 macrocells called logic array blocks (LABs). Each macrocell has a programmable–AND/fixed–OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with shareable expander and high–speed parallel expander product terms to provide up to 32 product terms per macrocell.

MAX 3000A devices provide programmable speed/power optimization. Speed–critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 3000A devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non–speed–critical signals are switching. The output drivers of all MAX 3000A devices can be set for 2.5 V or 3.3 V, and all input pins are 2.5–V, 3.3–V, and 5.0-V tolerant, allowing MAX 3000A devices to be used in mixed–voltage systems.

MAX 3000A devices are supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry–standard PC– and UNIX–workstation–based EDA tools. The software runs on Windows–based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.

For more information on development tools, see the *MAX+PLUS II Programmable Logic Development System & Software Data Sheet* and the *Quartus Programmable Logic Development System & Software Data Sheet*.

Functional Description

The MAX 3000A architecture includes the following elements:

- Logic array blocks (LABs)
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array (PIA)
- I/O control blocks

The MAX 3000A architecture includes four dedicated inputs that can be used as general–purpose inputs or as high–speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of MAX 3000A devices.

Figure 1. MAX 3000A Device Block Diagram
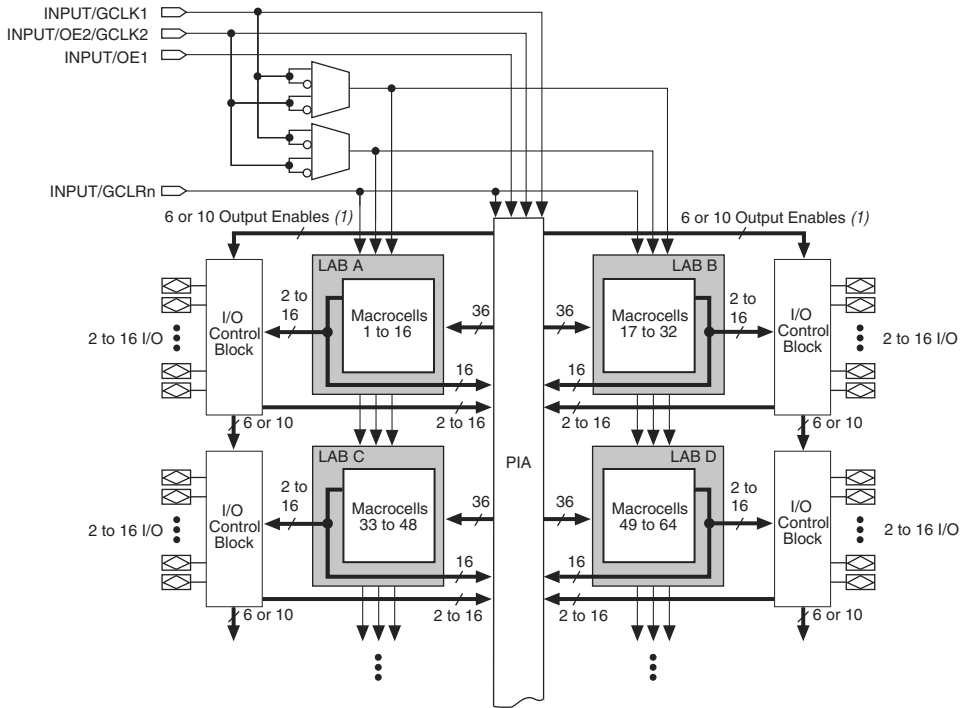
Note:

(1)   EPM3032A, EPM3064A, EPM3128A, and EPM3256A devices have six output enables. EPM3512A devices have 10 output enables.

Logic Array Blocks

The MAX 3000A device architecture is based on the linking of high–performance LABs. LABs consist of 16–macrocell arrays, as shown in Figure 1. Multiple LABs are linked together via the PIA, a global bus that is fed by all dedicated input pins, I/O pins, and macrocells.

Each LAB is fed by the following signals:

- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions

Macrocells

MAX 3000A macrocells can be individually configured for either sequential or combinatorial logic operation. Macrocells consist of three functional blocks: logic array, product–term select matrix, and programmable register. Figure 2 shows a MAX 3000A macrocell.

Figure 2. MAX 3000A Macrocell
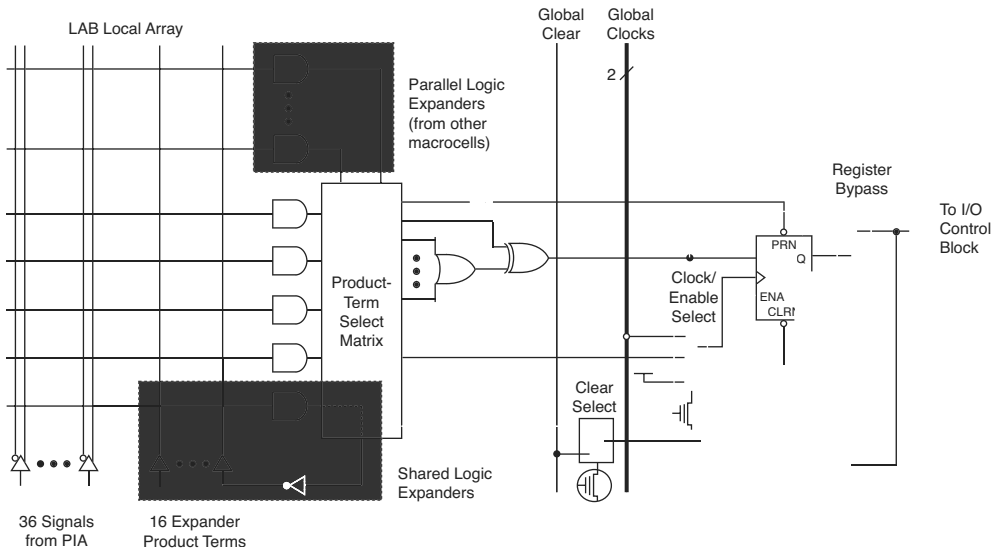
Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product–term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register preset, clock, and clock enable control functions.

Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

■ Shareable expanders, which are inverted product terms that are fed back into the logic array
■ Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product–term allocation according to the logic requirements of the design.

Altera Corporation

Figure 4. MAX 3000A Parallel Expanders

Unused product terms in a macrocell can be allocated to a neighboring macrocell.
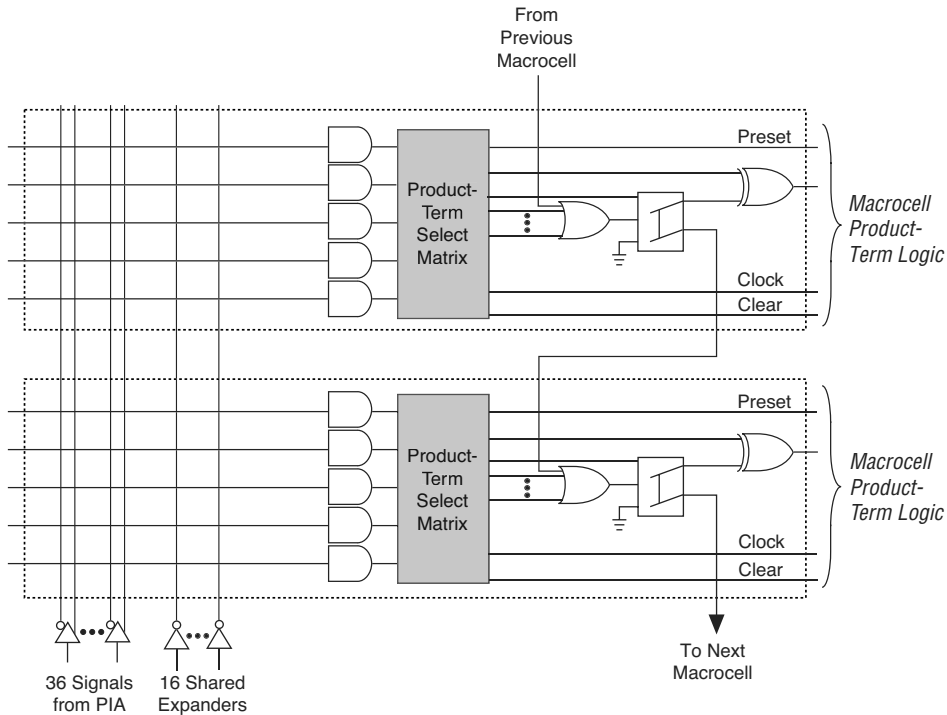
Programmable Interconnect Array

Logic is routed between LABs on the PIA. This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 3000A dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 5 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a two-input AND gate, which selects a PIA signal to drive into the LAB.

In–System Programmability

MAX 3000A devices can be programmed in–system via an industry–standard four–pin IEEE Std. 1149.1-1990 (JTAG) interface. In-system programmability (ISP) offers quick, efficient iterations during design development and debugging cycles. The MAX 3000A architecture internally generates the high programming voltages required to program its EEPROM cells, allowing in–system programming with only a single 3.3–V power supply. During in–system programming, the I/O pins are tri–stated and weakly pulled–up to eliminate board conflicts. The pull–up value is nominally 50 kΩ

MAX 3000A devices have an enhanced ISP algorithm for faster programming. These devices also offer an ISP_Done bit that ensures safe operation when in–system programming is interrupted. This ISP_Done bit, which is the last bit programmed, prevents all I/O pins from driving until the bit is programmed.

ISP simplifies the manufacturing flow by allowing devices to be mounted on a printed circuit board (PCB) with standard pick–and–place equipment before they are programmed. MAX 3000A devices can be programmed by downloading the information via in–circuit testers, embedded processors, the MasterBlaster communications cable, the ByteBlasterMV parallel port download cable, and the BitBlaster serial download cable. Programming the devices after they are placed on the board eliminates lead damage on high–pin–count packages (e.g., QFP packages) due to device handling. MAX 3000A devices can be reprogrammed after a system has already shipped to the field. For example, product upgrades can be performed in the field via software or modem.

The Jam STAPL programming and test language can be used to program MAX 3000A devices with in–circuit testers, PCs, or embedded processors.

For more information on using the Jam STAPL programming and test language, see *Application Note 88 (Using the Jam Language for ISP & ICR via an Embedded Processor)*, *Application Note 122 (Using Jam STAPL for ISP & ICR via an Embedded Processor)* and *AN 111 (Embedded Programming Using the 8051 and Jam Byte-Code)*.

The ISP circuitry in MAX 3000A devices is compliant with the IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

Programming Sequence

During in-system programming, instructions, addresses, and data are shifted into the MAX 3000A device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

1. *Enter ISP*. The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.

2. *Check ID*. Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.

3. *Bulk Erase*. Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.

4. *Program*. Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.

5. *Verify*. Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.

6. *Exit ISP*. An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 3000A Device

The time required to program a single MAX 3000A device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$

where:
t_{PROG} = Programming time
t_{PPULSE} = Sum of the fixed times to erase, program, and verify the EEPROM cells
$Cycle_{PTCK}$ = Number of TCK cycles to program a device
f_{TCK} = TCK frequency

The ISP times for a stand-alone verification of a single MAX 3000A device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$

where:
t_{VER} = Verify time
t_{VPULSE} = Sum of the fixed times to verify the EEPROM cells
$Cycle_{VTCK}$ = Number of TCK cycles to verify a device

The programming times described in Tables 4 through 6 are associated with the worst-case method using the enhanced ISP algorithm.

Table 4. MAX 3000A t_{PULSE} & Cycle$_{TCK}$ Values

Device	Programming		Stand-Alone Verification	
	t_{PPULSE} (s)	Cycle$_{PTCK}$	t_{VPULSE} (s)	Cycle$_{VTCK}$
EPM3032A	2.00	55,000	0.002	18,000
EPM3064A	2.00	105,000	0.002	35,000
EPM3128A	2.00	205,000	0.002	68,000
EPM3256A	2.00	447,000	0.002	149,000
EPM3512A	2.00	890,000	0.002	297,000

Tables 5 and 6 show the in-system programming and stand alone verification times for several common test clock frequencies.

Table 5. MAX 3000A In-System Programming Times for Different Test Clock Frequencies

Device	f_{TCK}								Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM3032A	2.01	2.01	2.03	2.06	2.11	2.28	2.55	3.10	s
EPM3064A	2.01	2.02	2.05	2.11	2.21	2.53	3.05	4.10	s
EPM3128A	2.02	2.04	2.10	2.21	2.41	3.03	4.05	6.10	s
EPM3256A	2.05	2.09	2.23	2.45	2.90	4.24	6.47	10.94	s
EPM3512A	2.09	2.18	2.45	2.89	3.78	6.45	10.90	19.80	s

Table 6. MAX 3000A Stand-Alone Verification Times for Different Test Clock Frequencies

Device	f_{TCK}								Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM3032A	0.00	0.01	0.01	0.02	0.04	0.09	0.18	0.36	s
EPM3064A	0.01	0.01	0.02	0.04	0.07	0.18	0.35	0.70	s
EPM3128A	0.01	0.02	0.04	0.07	0.14	0.34	0.68	1.36	s
EPM3256A	0.02	0.03	0.08	0.15	0.30	0.75	1.49	2.98	s
EPM3512A	0.03	0.06	0.15	0.30	0.60	1.49	2.97	5.94	s

Figure 7 shows the timing information for the JTAG signals.
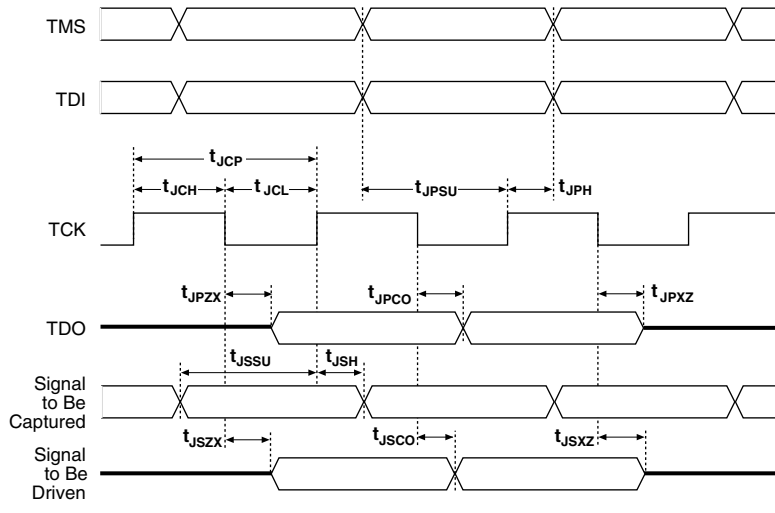
Figure 7. MAX 3000A JTAG Waveforms

Table 10 shows the JTAG timing parameters and values for MAX 3000A devices.

Table 10. JTAG Timing Parameters & Values for MAX 3000A Devices				
Symbol	**Parameter**	**Min**	**Max**	**Unit**
t$_{JCP}$	TCK clock period	100		ns
t$_{JCH}$	TCK clock high time	50		ns
t$_{JCL}$	TCK clock low time	50		ns
t$_{JPSU}$	JTAG port setup time	20		ns
t$_{JPH}$	JTAG port hold time	45		ns
t$_{JPCO}$	JTAG port clock to output		25	ns
t$_{JPZX}$	JTAG port high impedance to valid output		25	ns
t$_{JPXZ}$	JTAG port valid output to high impedance		25	ns
t$_{JSSU}$	Capture register setup time	20		ns
t$_{JSH}$	Capture register hold time	45		ns
t$_{JSCO}$	Update register clock to output		25	ns
t$_{JSZX}$	Update register high impedance to valid output		25	ns
t$_{JSXZ}$	Update register valid output to high impedance		25	ns

Open–Drain Output Option

MAX 3000A devices provide an optional open–drain (equivalent to open-collector) output for each I/O pin. This open–drain output enables the device to provide system–level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired–OR plane.

Open-drain output pins on MAX 3000A devices (with a pull-up resistor to the 5.0-V supply) can drive 5.0-V CMOS input pins that require a high V_{IH}. When the open-drain pin is active, it will drive low. When the pin is inactive, the resistor will pull up the trace to 5.0 V, thereby meeting CMOS requirements. The open-drain pin will only drive low or tri-state; it will never drive high. The rise time is dependent on the value of the pull-up resistor and load impedance. The I_{OL} current specification should be considered when selecting a pull-up resistor

Slew–Rate Control

The output buffer for each MAX 3000A I/O pin has an adjustable output slew rate that can be configured for low–noise or high–speed performance. A faster slew rate provides high–speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. When the configuration cell is turned off, the slew rate is set for low–noise performance. Each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin–by–pin basis. The slew rate control affects both the rising and falling edges of the output signal.

Design Security

All MAX 3000A devices contain a programmable security bit that controls access to the data programmed into the device. When this bit is programmed, a design implemented in the device cannot be copied or retrieved. This feature provides a high level of design security because programmed data within EEPROM cells is invisible. The security bit that controls this function, as well as all other programmed data, is reset only when the device is reprogrammed.

Generic Testing

MAX 3000A devices are fully tested. Complete testing of each programmable EEPROM bit and all internal logic elements ensures 100% programming yield. AC test measurements are taken under conditions equivalent to those shown in Figure 8. Test patterns can be used and then erased during early stages of the production flow.

Table 13. MAX 3000A Device Recommended Operating Conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CCINT}	Supply voltage for internal logic and input buffers	(10)	3.0	3.6	V
V_{CCIO}	Supply voltage for output drivers, 3.3–V operation		3.0	3.6	V
	Supply voltage for output drivers, 2.5–V operation		2.3	2.7	V
V_{CCISP}	Supply voltage during ISP		3.0	3.6	V
V_I	Input voltage	(3)	−0.5	5.75	V
V_O	Output voltage		0	V_{CCIO}	V
T_A	Ambient temperature	Commercial range	0	70	° C
		Industrial range	−40	85	° C
T_J	Junction temperature	Commercial range	0	90	° C
		Industrial range (11)	−40	105	° C
t_R	Input rise time			40	ns
t_F	Input fall time			40	ns

Table 14. MAX 3000A Device DC Operating Conditions   Note (4)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{IH}	High–level input voltage		1.7	5.75	V
V_{IL}	Low–level input voltage		−0.5	0.8	V
V_{OH}	3.3–V high–level TTL output voltage	I_{OH} = −8 mA DC, V_{CCIO} = 3.00 V (5)	2.4		V
	3.3–V high–level CMOS output voltage	I_{OH} = −0.1 mA DC, V_{CCIO} = 3.00 V (5)	V_{CCIO} − 0.2		V
	2.5–V high–level output voltage	I_{OH} = −100 µA DC, V_{CCIO} = 2.30 V (5)	2.1		V
		I_{OH} = −1 mA DC, V_{CCIO} = 2.30 V (5)	2.0		V
		I_{OH} = −2 mA DC, V_{CCIO} = 2.30 V (5)	1.7		V
V_{OL}	3.3–V low–level TTL output voltage	I_{OL} = 8 mA DC, V_{CCIO} = 3.00 V (6)		0.4	V
	3.3–V low–level CMOS output voltage	I_{OL} = 0.1 mA DC, V_{CCIO} = 3.00 V (6)		0.2	V
	2.5–V low–level output voltage	I_{OL} = 100 µA DC, V_{CCIO} = 2.30 V (6)		0.2	V
		I_{OL} = 1 mA DC, V_{CCIO} = 2.30 V (6)		0.4	V
		I_{OL} = 2 mA DC, V_{CCIO} = 2.30 V (6)		0.7	V
I_I	Input leakage current	V_I = −0.5 to 5.5 V (7)	−10	10	µA
I_{OZ}	Tri–state output off–state current	V_I = −0.5 to 5.5 V (7)	−10	10	µA
R_{ISP}	Value of I/O pin pull–up resistor when programming in–system or during power–up	V_{CCIO} = 2.3 to 3.6 V (8)	20	74	kΩ

Table 19. EPM3064A Internal Timing Parameters (Part 2 of 2)   Note (1)

Symbol	Parameter	Conditions	Speed Grade						Unit
			−4		−7		−10		
			Min	Max	Min	Max	Min	Max	
t_{CLR}	Register clear time			1.3		2.1		2.9	ns
t_{PIA}	PIA delay	(2)		1.0		1.7		2.3	ns
t_{LPA}	Low–power adder	(5)		3.5		4.0		5.0	ns

Table 20. EPM3128A External Timing Parameters   Note (1)

Symbol	Parameter	Conditions	Speed Grade						Unit
			−5		−7		−10		
			Min	Max	Min	Max	Min	Max	
t_{PD1}	Input to non–registered output	C1 = 35 pF (2)		5.0		7.5		10	ns
t_{PD2}	I/O input to non–registered output	C1 = 35 pF (2)		5.0		7.5		10	ns
t_{SU}	Global clock setup time	(2)	3.3		4.9		6.6		ns
t_H	Global clock hold time	(2)	0.0		0.0		0.0		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.4	1.0	5.0	1.0	6.6	ns
t_{CH}	Global clock high time		2.0		3.0		4.0		ns
t_{CL}	Global clock low time		2.0		3.0		4.0		ns
t_{ASU}	Array clock setup time	(2)	1.8		2.8		3.8		ns
t_{AH}	Array clock hold time	(2)	0.2		0.3		0.4		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	4.9	1.0	7.1	1.0	9.4	ns
t_{ACH}	Array clock high time		2.0		3.0		4.0		ns
t_{ACL}	Array clock low time		2.0		3.0		4.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns
t_{CNT}	Minimum global clock period	(2)		5.2		7.7		10.2	ns
f_{CNT}	Maximum internal global clock frequency	(2), (4)	192.3		129.9		98.0		MHz
t_{ACNT}	Minimum array clock period	(2)		5.2		7.7		10.2	ns

Table 20. EPM3128A External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			−5		−7		−10		
			Min	Max	Min	Max	Min	Max	
f_ACNT	Maximum internal array clock frequency	(2), (4)	192.3		129.9		98.0		MHz

Table 21. EPM3128A Internal Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			−5		−7		−10		
			Min	Max	Min	Max	Min	Max	
t_IN	Input pad and buffer delay			0.7		1.0		1.4	ns
t_IO	I/O input pad and buffer delay			0.7		1.0		1.4	ns
t_SEXP	Shared expander delay			2.0		2.9		3.8	ns
t_PEXP	Parallel expander delay			0.4		0.7		0.9	ns
t_LAD	Logic array delay			1.6		2.4		3.1	ns
t_LAC	Logic control array delay			0.7		1.0		1.3	ns
t_IOE	Internal output enable delay			0.0		0.0		0.0	ns
t_OD1	Output buffer and pad delay, slow slew rate = off V_CCIO = 3.3 V	C1 = 35 pF		0.8		1.2		1.6	ns
t_OD2	Output buffer and pad delay, slow slew rate = off V_CCIO = 2.5 V	C1 = 35 pF		1.3		1.7		2.1	ns
t_OD3	Output buffer and pad delay, slow slew rate = on V_CCIO = 2.5 V or 3.3 V	C1 = 35 pF		5.8		6.2		6.6	ns
t_ZX1	Output buffer enable delay, slow slew rate = off V_CCIO = 3.3 V	C1 = 35 pF		4.0		4.0		5.0	ns
t_ZX2	Output buffer enable delay, slow slew rate = off V_CCIO = 2.5 V	C1 = 35 pF		4.5		4.5		5.5	ns
t_ZX3	Output buffer enable delay, slow slew rate = on V_CCIO = 2.5 V or 3.3 V	C1 = 35 pF		9.0		9.0		10.0	ns
t_XZ	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0	ns

Table 22. EPM3256A External Timing Parameters   *Note (1)*

Symbol	Parameter	Conditions	Speed Grade				Unit
			−7		**−10**		
			Min	**Max**	**Min**	**Max**	
t$_{CNT}$	Minimum global clock period	*(2)*		7.9		10.5	ns
f$_{CNT}$	Maximum internal global clock frequency	*(2), (4)*	126.6		95.2		MHz
t$_{ACNT}$	Minimum array clock period	*(2)*		7.9		10.5	ns
f$_{ACNT}$	Maximum internal array clock frequency	*(2), (4)*	126.6		95.2		MHz

Table 23. EPM3256A Internal Timing Parameters (Part 1 of 2)   *Note (1)*

Symbol	Parameter	Conditions	Speed Grade				Unit
			−7		**−10**		
			Min	**Max**	**Min**	**Max**	
t_{IN}	Input pad and buffer delay			0.9		1.2	ns
t_{IO}	I/O input pad and buffer delay			0.9		1.2	ns
t_{SEXP}	Shared expander delay			2.8		3.7	ns
t_{PEXP}	Parallel expander delay			0.5		0.6	ns
t_{LAD}	Logic array delay			2.2		2.8	ns
t_{LAC}	Logic control array delay			1.0		1.3	ns
t_{IOE}	Internal output enable delay			0.0		0.0	ns
t_{OD1}	Output buffer and pad delay, slow slew rate = off V$_{CCIO}$ = 3.3 V	C1 = 35 pF		1.2		1.6	ns
t_{OD2}	Output buffer and pad delay, slow slew rate = off V$_{CCIO}$ = 2.5 V	C1 = 35 pF		1.7		2.1	ns
t_{OD3}	Output buffer and pad delay, slow slew rate = on V$_{CCIO}$ = 2.5 V or 3.3 V	C1 = 35 pF		6.2		6.6	ns
t_{ZX1}	Output buffer enable delay, slow slew rate = off V$_{CCIO}$ = 3.3 V	C1 = 35 pF		4.0		5.0	ns
t_{ZX2}	Output buffer enable delay, slow slew rate = off V$_{CCIO}$ = 2.5 V	C1 = 35 pF		4.5		5.5	ns

Table 24. EPM3512A External Timing Parameters   Note (1)

Symbol	Parameter	Conditions	Speed Grade				Unit
			-7		-10		
			Min	Max	Min	Max	
t_{AH}	Array clock hold time	(2)	0.2		0.3		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	7.8	1.0	10.4	ns
t_{ACH}	Array clock high time		3.0		4.0		ns
t_{ACL}	Array clock low time		3.0		4.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	(3)	3.0		4.0		ns
t_{CNT}	Minimum global clock period	(2)		8.6		11.5	ns
f_{CNT}	Maximum internal global clock frequency	(2), (4)	116.3		87.0		MHz
t_{ACNT}	Minimum array clock period	(2)		8.6		11.5	ns
f_{ACNT}	Maximum internal array clock frequency	(2), (4)	116.3		87.0		MHz

Table 25. EPM3512A Internal Timing Parameters (Part 1 of 2)   Note (1)

Symbol	Parameter	Conditions	Speed Grade				Unit
			-7		-10		
			Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.7		0.9	ns
t_{IO}	I/O input pad and buffer delay			0.7		0.9	ns
t_{FIN}	Fast input delay			3.1		3.6	ns
t_{SEXP}	Shared expander delay			2.7		3.5	ns
t_{PEXP}	Parallel expander delay			0.4		0.5	ns
t_{LAD}	Logic array delay			2.2		2.8	ns
t_{LAC}	Logic control array delay			1.0		1.3	ns
t_{IOE}	Internal output enable delay			0.0		0.0	ns
t_{OD1}	Output buffer and pad delay, slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF		1.0		1.5	ns
t_{OD2}	Output buffer and pad delay, slow slew rate = off V_{CCIO} = 2.5 V	C1 = 35 pF		1.5		2.0	ns

### Table 25. EPM3512A Internal Timing Parameters (Part 2 of 2)   Note (1)

| Symbol	Parameter	Conditions	Speed Grade				Unit
			-7		-10		
			Min	Max	Min	Max	
t_{OD3}	Output buffer and pad delay, slow slew rate = on V_{CCIO} = 2.5 V or 3.3 V	C1 = 35 pF		6.0		6.5	ns
t_{ZX1}	Output buffer enable delay, slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF		4.0		5.0	ns
t_{ZX2}	Output buffer enable delay, slow slew rate = off V_{CCIO} = 2.5 V	C1 = 35 pF		4.5		5.5	ns
t_{ZX3}	Output buffer enable delay, slow slew rate = on V_{CCIO} = 3.3 V	C1 = 35 pF		9.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		5.0	ns
t_{SU}	Register setup time		2.1		3.0		ns
t_{H}	Register hold time		0.6		0.8		ns
t_{FSU}	Register setup time of fast input		1.6		1.6		ns
t_{FH}	Register hold time of fast input		1.4		1.4		ns
t_{RD}	Register delay			1.3		1.7	ns
t_{COMB}	Combinatorial delay			0.6		0.8	ns
t_{IC}	Array clock delay			1.8		2.3	ns
t_{EN}	Register enable time			1.0		1.3	ns
t_{GLOB}	Global control delay			1.7		2.2	ns
t_{PRE}	Register preset time			1.0		1.4	ns
t_{CLR}	Register clear time			1.0		1.4	ns
t_{PIA}	PIA delay	(2)		3.0		4.0	ns
t_{LPA}	Low-power adder	(5)		4.5		5.0	ns

Notes to tables:

(1)   These values are specified under the recommended operating conditions, as shown in Table 13 on page 23. See Figure 11 on page 27 for more information on switching waveforms.

(2)   These values are specified for a PIA fan–out of one LAB (16 macrocells). For each additional LAB fan–out in these devices, add an additional 0.1 ns to the PIA timing value.

(3)   This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.

(4)   These parameters are measured with a 16–bit loadable, enabled, up/down counter programmed into each LAB.

(5)   The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, t_{SEXP}, **t_{ACL}**, and **t_{CPPW}** parameters for macrocells running in low–power mode.

Figure 12. I$_{CC}$ vs. Frequency for MAX 3000A Devices

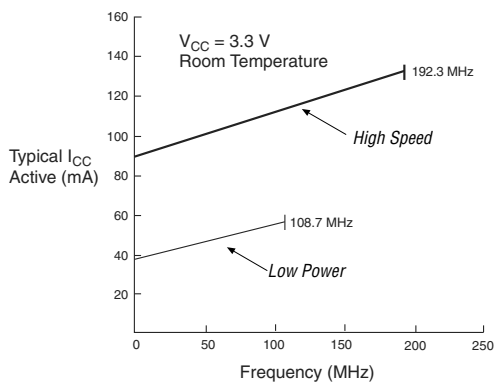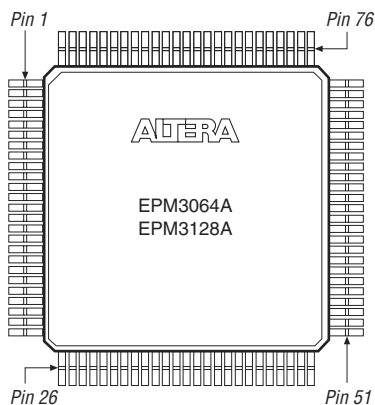**EPM3032A**
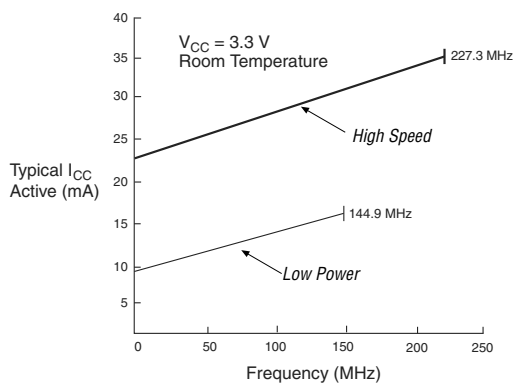
EPM3064A
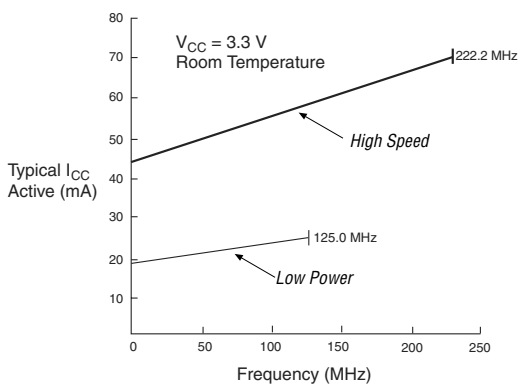
EPM3128A

Figure 15. 100–Pin TQFP Package Pin–Out Diagram

Package outline not drawn to scale.

Figure 16. 144–Pin TQFP Package Pin–Out Diagram
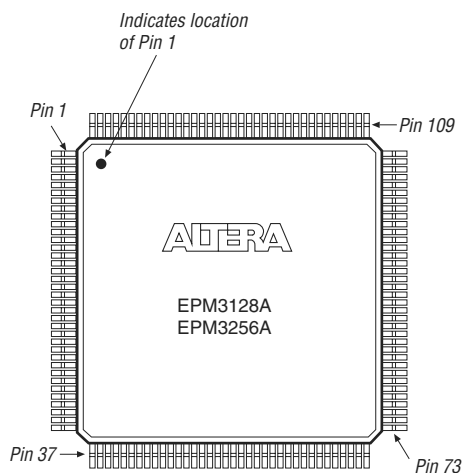
Package outline not drawn to scale.

Figure 17. 208–Pin PQFP Package Pin–Out Diagram

Package outline not drawn to scale.